



Features

- Available with any-frequency output
 Available CMOS, LVPECL, frequencies from 10 to 810 MHz
- 3rd generation DSPLL[®] with superior jitter performance: 1 ps max jitter
- Better frequency stability than SAWbased oscillators
- Internal fundamental mode crystal ensures high reliability

Applications

- SONET/SDH (OC-3/12/48)
- Networking
- SD/HD SDI/3G SDI video

Description

- Test and measurement
- Storage

FPGA/ASIC clock generation

LVDS, and CML outputs

Pb-free/RoHS-compliant

-40 to +85 °C operating

package and pinout

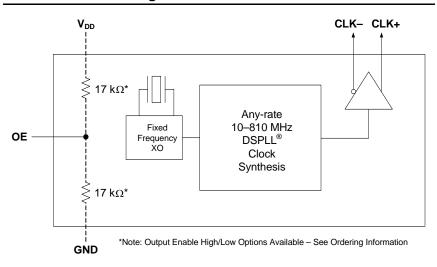
temperature range

Industry-standard 5 x 7 mm

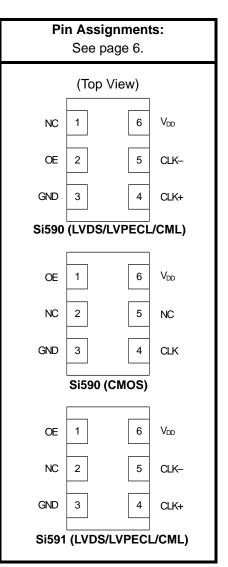
3.3, 2.5, and 1.8 V supply options

The Si590/591 XO utilizes Silicon Laboratories' advanced DSPLL[®] circuitry to provide a low jitter clock at high frequencies. The Si590/591 supports any frequency from 10 to 810 MHz. Unlike a traditional XO, where a unique crystal is required for each output frequency, the Si590/591 uses one fixed crystal to provide a wide range of output frequencies. This IC based approach allows the crystal resonator to provide exceptional frequency stability and reliability. In addition, DSPLL clock synthesis provides superior supply noise rejection, simplifying the task of generating low jitter clocks in noisy environments typically found in communication systems. The Si590/591 IC based XO is factory configurable for a wide variety of user specifications including frequency, supply voltage, output format, and stability. Specific configurations are factory programmed at time of shipment, thereby eliminating long lead times associated with custom oscillators.

Functional Block Diagram







1. Electrical Specifications

Table 1. Recommended Operating Conditions

Parameter	Symbol	Test Condition	Min	Тур	Max	Units
Supply Voltage ¹	V _{DD}	3.3 V option	2.97	3.3	3.63	
		2.5 V option	2.25	2.5	2.75	V
		1.8 V option	1.71	1.8	1.89	
Supply Current	I _{DD}	Output enabled				
		LVPECL		110	125	
		CML		100	110	
		LVDS		90	100	mA
		CMOS	—	80	90	
		Tristate mode	—	60	75	-
Output Enable (OE) ²		V _{IH}	0.75 x V _{DD}	_		V
		V _{IL}	—		0.5	
Operating Temperature Range	T _A		-40		85	٥C
Notos:	•		•		•	•

Notes:

1. Selectable parameter specified by part number. See Section 3. "Ordering Information" on page 7 for further details.

2. OE pin includes an internal 17 k Ω pullup resistor to V_{DD} for output enable active high or a 17 k Ω pull-down resistor to

GND for output enable active low. See 3. "Ordering Information" on page 7.

Table 2. CLK± Output Frequency Characteristics

Parameter	Symbol	Test Condition	Min	Тур	Max	Units
Nominal Frequency ^{1,2}	f _O	LVPECL/LVDS/CML	10	—	810	MHz
		CMOS	10		160	
Initial Accuracy	f _i	Measured at +25 °C at time of shipping	_	±1.5	_	ppm
Total Stability		Note 3, second option code "D"			±20	ppm
		Note 3, second option code "C"		_	±30	ppm
		Note 4, second option code "B"		_	±50	ppm
		Note 4, second option code "A"			±100	ppm
Temperature Stability		second option code "D"			±7	ppm
		second option code "C"			±20	ppm
		second option code "B"	_		±25	ppm
		second option code "A"		—	±50	ppm
Powerup Time ⁵	tosc			_	10	ms

Notes:

- 1. See Section 3. "Ordering Information" on page 7 for further details.
- 2. Specified at time of order by part number.
- 3. Includes initial accuracy, temperature, shock, vibration, power supply and load drift, and 10 years aging at 40 °C. See 3. "Ordering Information" on page 7.
- 4. Includes initial accuracy, temperature, shock, vibration, power supply and load drift, and 15 years aging at 70 °C. See 3. "Ordering Information" on page 7.
- 5. Time from powerup or tristate mode to f_{O} .



Parameter	Symbol	Test Condition	Min	Тур	Max	Units
LVPECL Output Option ¹	Vo	mid-level	V _{DD} – 1.42	_	V _{DD} – 1.25	V
	V _{OD}	swing (diff)	1.1	_	1.9	V _{PP}
	V _{SE}	swing (single-ended)	0.55	_	0.95	V _{PP}
LVDS Output Option ²	V _O	mid-level	1.125	1.20	1.275	V
	V _{OD}	swing (diff)	0.5	0.7	0.9	V _{PP}
	V	2.5/3.3 V option mid-level	—	V _{DD} – 1.30	—	V
\mathbf{O}	Vo	1.8 V option mid-level	_	V _{DD} - 0.36		V
CML Output Option ²	V	2.5/3.3 V option swing (diff)	1.10	1.50	1.90	M
	V _{OD}	1.8 V option swing (diff)	0.35	0.425	0.50	V _{PP}
CMOS Output Option ³	V _{OH}		0.8 x V _{DD}	—	V _{DD}	V
	V _{OL}		—	—	0.4	v
Rise/Fall time (20/80%)	t _{R,} t _F	LVPECL/LVDS/CML	—	_	350	ps
		CMOS with $C_L = 15 \text{ pF}$		2		ns
Symmetry (duty cycle)	SYM	LVPECL: V _{DD} - 1.3 V (diff) LVDS: 1.25 V (diff) CMOS: V _{DD} /2	45	_	55	%

1. 50 Ω to V_{DD} – 2.0 V. **2.** R_{term} = 100 Ω (differential). **3.** C_L = 15 pF. Sinking or sourcing 12 mA for V_{DD} = 3.3 V, 6 mA for V_{DD} = 2.5 V, 3 mA for V_{DD} = 1.8 V.

Table 4. CLK± Output Phase Jitter

Parameter	Symbol	Test Condition	Min	Тур	Max	Units
Phase Jitter (RMS) ¹ for 50 MHz ≤ F _{OUT} ≤ 810 MHz (LVPECL/LVDS/CML)	фJ	12 kHz to 20 MHz	_	0.5	1.0	ps
Phase Jitter (RMS) ¹ (LVPECL/LVDS/CML)	фј	12 kHz to 20 MHz, 155.52 MHz output frequency	_	0.4	0.7	ps
Phase Jitter (RMS) ² for 50 MHz ≤ F _{OUT} ≤ 160 MHz (CMOS)	фJ	12 kHz to 20 MHz		0.6	1.0	ps

Notes:

1. Refer to AN256 for further information.

2. Single-ended CMOS output phase jitter measured using 33 Ω series termination into 50 Ω phase noise test equipment. 3.3 V supply voltage option only.



Table 5. CLK± Output Period Jitter

Parameter	Symbol	Test Condition	Min	Тур	Max	Units
Period Jitter*	J _{PER}	RMS	—		3	ps
		Peak-to-Peak			35	
*Note: Any output mode, including C	CMOS, LVPI	ECL, LVDS, CML. N = 1000 cycles.	Refer to AN	279 for furt	her informa	ation.

Table 6. Environmental Compliance and Package Information

Parameter	Conditions/Test Method
Mechanical Shock	MIL-STD-883, Method 2002
Mechanical Vibration	MIL-STD-883, Method 2007
Solderability	MIL-STD-883, Method 2003
Gross and Fine Leak	MIL-STD-883, Method 1014
Resistance to Solder Heat	MIL-STD-883, Method 2036
Moisture Sensitivity Level	J-STD-020, MSL1
Contact Pads	Gold over Nickel

Table 7. Thermal Characteristics

(Typical values T_A = 25 °C, V_{DD} = 3.3 V)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Thermal Resistance Junction to Ambient	θ_{JA}	Still Air	_	84.6	_	°C/W
Thermal Resistance Junction to Case	θ_{JC}	Still Air	_	38.8	_	°C/W
Ambient Temperature	T _A		-40	_	85	°C
Junction Temperature	Т _Ј				125	°C



Table 8. Absolute Maximum Ratings¹

Parameter	Symbol	Rating	Units
Maximum Operating Temperature	T _{AMAX}	85	°C
Supply Voltage, 1.8 V Option	V _{DD}	-0.5 to +1.9	V
Supply Voltage, 2.5/3.3 V Option	V _{DD}	-0.5 to +3.8	V
Input Voltage (any input pin)	VI	-0.5 to V _{DD} + 0.3	V
Storage Temperature	Τ _S	-55 to +125	°C
ESD Sensitivity (HBM, per JESD22-A114)	ESD	2500	V
Soldering Temperature (Pb-free profile) ²	T _{PEAK}	260	°C
Soldering Temperature Time @ T _{PEAK} (Pb-free profile) ²	t _P	20–40	seconds

Notes:

1. Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Functional operation or specification compliance is not implied at these conditions. Exposure to maximum rating conditions for extended periods may affect device reliability.

2. The device is compliant with JEDEC J-STD-020C. Refer to Si5xx Packaging FAQ available for download at www.silabs.com/VCXO for further information, including soldering profiles.



Si590/591

2. Pin Descriptions

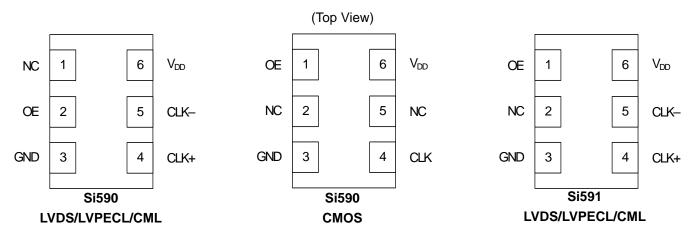


Table 9. Pinout for Si590 Series

Pin	Symbol	LVDS/LVPECL/CML Function	CMOS Function
1	OE*	No connection Make no external connection to this pin	Output enable
2	OE*	Output enable	No connection Make no external connection to this pin
3	GND	Electrical and Case Ground	Electrical and Case Ground
4	CLK+	Oscillator Output	Oscillator Output
5	CLK-	Complementary Output	No connection Make no external connection to this pin
6	V _{DD}	Power Supply Voltage	Power Supply Voltage
*Note		es an internal 17 k Ω pullup resistor to V _{DD} for outputit enable active low. See 3. "Ordering Information" of	

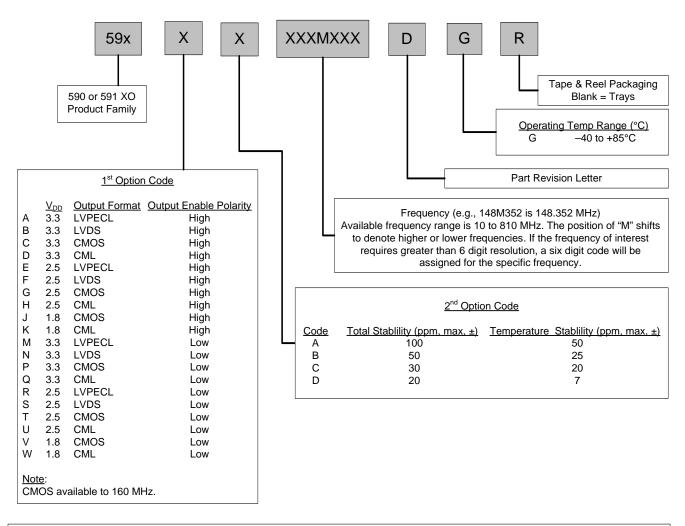
Table 10. Pinout for Si591 Series

Pin	Symbol	LVDS/LVPECL/CML Function
1	OE*	Output enable
2	No connection Make no external connection to this pin	No connection Make no external connection to this pin
3	GND	Electrical and Case Ground
4	CLK+	Oscillator Output
5	CLK-	Complementary output
6	V _{DD}	Power Supply Voltage
	DE pin includes an internal 17 k Ω pullup resistor SND for output enable active low. See 3. "Orderi	r to V_{DD} for output enable active high or a 17 k Ω pulldown resistor to ng Information" on page 7.



3. Ordering Information

The Si590/591 XO supports a variety of options including frequency, temperature stability, output format, and V_{DD}. Specific device configurations are programmed into the Si590/591 at time of shipment. Configurations can be specified using the Part Number Configuration chart below. Silicon Laboratories provides a web browser-based part number configuration utility to simplify this process. Refer to www.silabs.com/VCXOPartNumber to access this tool and for further ordering instructions. The Si590 and Si591 XO series are supplied in an industry-standard, RoHS compliant, 6-pad, 5×7 mm package. The Si591 Series supports an alternate OE pinout (pin #1) for LVPECL, LVDS, and CML output formats. See Tables 9 and 10 for the pinout differences between the Si590 and Si591 series.



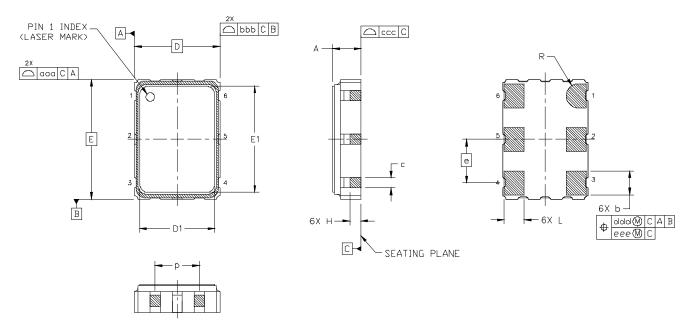
Example P/N: 590BB148M352DGR is a 5 x 7 XO in a 6 pad package. The frequency is 148.352 MHz, with a 3.3 V supply, LVDS output, and Output Enable active high polarity. Overall stability is specified as \pm 50 ppm. The device is specified for -40 to +85 °C ambient temperature range operation and is shipped in tape and reel format.

Figure 1. Part Number Convention



4. Outline Diagram and Suggested Pad Layout

Figure 2 illustrates the package details for the Si590/591. Table 11 lists the values for the dimensions shown in the illustration.





Dimension	Min	Nom	Max			
A	1.50	1.65	1.80			
b	1.30	1.40	1.50			
С	0.50	0.60	0.70			
D		5.00 BSC				
D1	4.30	4.40	4.50			
е		2.54 BSC				
E	7.00 BSC					
E1	6.10	6.20	6.30			
Н	0.55	0.65	0.75			
L	1.17	1.27	1.37			
р	1.80	—	2.60			
R		0.70 REF				
aaa		0.15				
bbb		0.15				
CCC	0.10					
ddd		0.10				
eee		0.50				

Table 11. Package Diagram Dimensions (mm)



5. 6-Pin PCB Land Pattern

Figure 3 illustrates the 6-pin PCB land pattern for the Si590/591. Table 12 lists the values for the dimensions shown in the illustration.

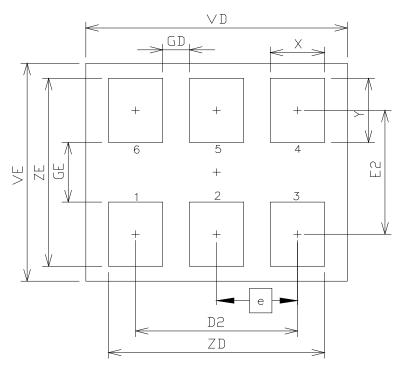


Figure 3. Si590/591 PCB Land Pattern

Dimension	Min	Max
D2	5.08 REF	
е	2.54 BSC	
E2	4.15 REF	
GD	0.84	_
GE	2.00	_
VD	8.20 REF	
VE	7.30 REF	
X	1.70 TYP	
Y	2.15 REF	
ZD	_	6.78
ZE		6.30

Table 12. PCB Land Pattern Dimensions (mm)

1. Dimensioning and tolerancing per the ANSI Y14.5M-1994 specification.

2. Land pattern design based on IPC-7351 guidelines.

3. All dimensions shown are at maximum material condition (MMC).

4. Controlling dimension is in millimeters (mm).



6. Si590/Si591 Top Marking

Figure 4 illustrates the mark specification for the Si590/Si591. Table 13 lists the line information.

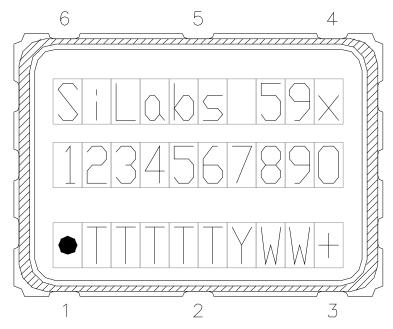


Figure 4. Top Mark Specification

Table 13. Si59x Top Mark Description

Line	Position	Description	
1	1–10	"SiLabs"+ Part Family Number, 59x (First 3 characters in part number where x indicates a 590 device and $x = 1$ indicates a 591 device)	
2	1–10	Si590, Si591: Option1 + Option2 + Freq(7) + Temp Si590/Si591 w/ 8-digit resolution: Option1 + Option2 + ConfigNum(6) + Temp	
3	Trace Code		
	Position 1	Pin 1 orientation mark (dot)	
	Position 2	Product Revision (D)	
	Position 3–6	Tiny Trace Code (4 alphanumeric characters per assembly release instructions)	
	Position 7	Year (least significant year digit), to be assigned by assembly site (ex: 2009 = 9)	
	Position 8–9	Calendar Work Week number (1–53), to be assigned by assembly site	
	Position 10	"+" to indicate Pb-Free and RoHS-compliant	



DOCUMENT CHANGE LIST

Revision 0.2 to Revision 0.25

- Total Stability Maximum changed to ±30 in Table 2 on page 2.
- Total Stability Maximum changed to ±30 in Figure 1 on page 7.

Revision 0.25 to Revision 0.3

- Updated Table 4 on page 3 by adding the 155.51 MHz "Phase Jitter (RMS) (LVPECL/LVDS/CML)" row.
- Updated and clarified Table 6 on page 4 to correct typos and include the "Moisture Sensitivity Level" and "Contact Pads" rows.
- Corrected BSC value in rows D and E in Table 11 on page 8.

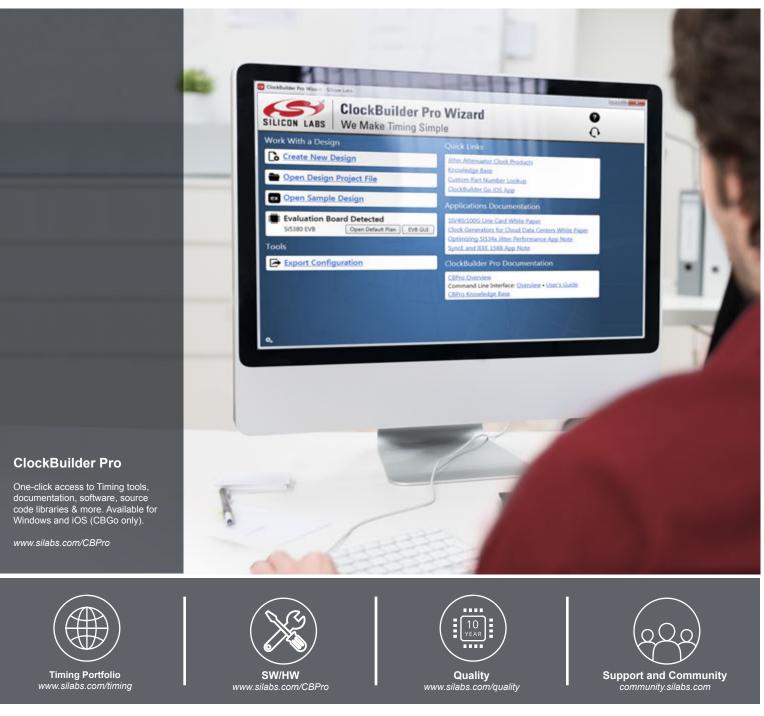
Revision 0.3 to Revision 0.4

Added ±7 ppm temperature stability ordering option in Table 4 on page 3 and Figure 1 on page 7.

Revision 0.4 to Revision 1.0

- Updated 2.5 V/3.3 V and 1.8 V CML output level specifications in Table 3 on page 3.
- Updated Si590/591 devices to support frequencies up to 810 MHz for LVPECL, LVDS, and CML outputs.
- Separated 1.8 V, 2.5 V/3.3 V supply voltage. specifications for CML output in Table 3 on page 3.
- Updated Note 1 of Table 4 on page 3 to refer to AN256.
- Updated Table 4 on page 3.
 - Updated phase jitter specification.
- Updated Table 6 on page 4 to include the "Moisture Sensitivity Level" and "Contact Pads" rows.
- Updated Figure 3 and Table 13 on page 10 to reflect specific marking information.
- Added Table 7, "Thermal Characteristics," on page 4.
- Rearranged sections to conform to new quality standard.





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